

USSN 10/608,606

PATENT

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In the Specification

Substitute paragraphs for the Specification are set forth below:

[0001] This application is related to a simultaneously-filed United States patent application serial number ~~10/xxx,xxx~~ 10/608,605 entitled *Packaging Device for*
15 *Semiconductor Die and Semiconductor Device Incorporating Same* of inventors Kong Weng Lee, Kee Yean Ng, Yew Cheong Kuan, Cheng Why Tan and Gin Ghee Tan, ~~attorney docket~~
~~number 70030259-1.~~

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